



SLOVENSKI STANDARD

SIST EN 60286-3:2013

01-oktober-2013

Pakiranje komponent za avtomatsko ravnanje - 3. del: Pakiranje komponent za površinsko montažo na neprekinjenih trakovih

Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes

Gurtung und Magazinierung von Bauelementen für die automatische Verarbeitung - Teil 3: Gurtung von oberflächenmontierbaren Bauelementen auf Endlosgurten

Emballage de composants pour opérations automatisées - Partie 3: Emballage des composants pour montage en surface en bandes continues

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Ta slovenski standard je istoveten z: EN 60286-3:2013

ICS:

31.020	Elektronske komponente na splošno	Electronic components in general
55.060	Tulci. Vretena	Spools. Bobbins

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en

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60286-3

August 2013

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English version

**Packaging of components for automatic handling -
Part 3: Packaging of surface mount components on continuous tapes
(IEC 60286-3:2013)**

Emballage de composants pour
opérations automatisées -
Partie 3: Emballage des composants pour
montage en surface en bandes continues
(CEI 60286-3:2013)

Gurtung und Magazinierung von
Bauelementen für die automatische
Verarbeitung -
Teil 3: Gurtung von
oberflächenmontierbaren Bauelementen
auf Endlogurten
(IEC 60286-3:2013)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 40/2200/FDIS, future edition 5 of IEC 60286-3, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60286-3:2013.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2014-03-21
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2016-06-21

This document supersedes EN 60286-3:2007.

EN 60286-3:2013 includes the following significant technical changes with respect to EN 60286-3:2007:

- a) integration of EN 60286-3-1:2009 as type 1b (Packaging of surface mount components on continuous pressed carrier tapes);
- b) integration of EN 60286-3-2:2009 as type 2b (Packaging of surface mount components on blister carrier tapes 4 mm in width).

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Endorsement notice

The text of the International Standard IEC 60286-3:2013 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60286-3-1:2009	NOTE	Harmonised as EN 60286-3-1:2009 (not modified).
IEC 60286-3-2:2009	NOTE	Harmonised as EN 60286-3-2:2009 (not modified).
IEC/TR 62258-3	NOTE	Harmonised as CLC/TR 62258-3.
ISO 11469	NOTE	Harmonised as EN ISO 11469.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-2	-	Mechanical standardization of semiconductor devices - Part 2: Dimensions	-	-
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC/TR 61340-5-2	-	Electrostatics - Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide	CLC/TR 61340-5-2	-

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IEC 60286-3

Edition 5.0 2013-05

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Packaging of components for automatic handling –
Part 3: Packaging of surface mount components on continuous tapes**

**Emballage de composants pour opérations automatisées –
Partie 3: Emballage des composants pour montage en surface en bandes
continues**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 3: Packaging of surface mount components
on continuous tapes**

FOREWORD

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International Standard IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This fifth edition cancels and replaces the fourth edition, published in 2007, as well as IEC 60286-3-1, published in 2009 and IEC 60286-3-2, published in 2009. It constitutes a full layout revision. In addition, this edition includes the following significant technical changes with respect to the previous edition:

- a) integration of IEC 60286-3-1:2009 as type 1b (Packaging of surface mount components on continuous pressed carrier tapes);
- b) integration of IEC 60286-3-2:2009 as type 2b (Packaging of surface mount components on blister carrier tapes 4 mm in width).

The text of this standard is based on the following documents:

FDIS	Report on voting
40/2200/FDIS	40/2233/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all the parts of the IEC 60286 series, under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components and singulated dies for test purposes and other operations.

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